AMD Xilinx - XC2VP100-5FF1704I Datasheet

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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	11024
Number of Logic Elements/Cells	99216
Total RAM Bits	8183808
Number of I/O	1040
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1704-BBGA, FCBGA
Supplier Device Package	1704-FCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp100-5ff1704i

Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

DS083 (v5.0) June 21, 2011 **Product Specification**

Virtex-II Pro[1] Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

Virtex-II Pro DC Characteristics

Table 1: **Absolute Maximum Ratings**

Symbol	Description[1]		Virtex-II Pro X	Virtex-II Pro	Units
V_{CCINT}	Internal supply voltage relative to GND		–0.5 to 1.6		V
V_{CCAUX}	Auxiliary supply voltage relative to GND		–0.5 to 3.0		V
V_{CCO}	Output drivers supply voltage relative to GND		–0.5 to 3.75		V
V_{BATT}	Key memory battery backup supply		–0.5 to 4.05		V
V_{REF}	Input reference voltage		–0.3 to 3.75		V
V_{IN}	3.3V I/O input voltage relative to GND (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
V_{TS}	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
AVCCAUXRX	Receive auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 2.0	–0.5 to 3.0	V
AVCCAUXTX	Transmit auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 3.0	–0.5 to 3.0	V
V_{TRX}	Terminal receive supply voltage relative to GND		–0.5 to 3.0	–0.5 to 3.0	V
V_{TTX}	Terminal transmit supply voltage relative to GND		–0.5 to 1.6	–0.5 to 3.0	V
T_{STG}	Storage temperature (ambient)		–65 to +150		°C
T_{SOL}	Maximum soldering temperature[2]	All regular FG/FF flip-chip packages	+220		°C
		Pb-free FGG256 wire-bond package	N/A	+260	°C
		Pb-free FGG456 and FGG676 wire-bond packages	N/A	+250	°C
T_J	Maximum junction temperature[2]		+125		°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. For soldering guidelines and thermal considerations, see the **Device Packaging and Thermal Characteristics Guide** information on the Xilinx website.
3. 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to **XAPP659** for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

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Virtex-II Pro Switching Characteristics

Switching characteristics are specified on a per-speed-grade basis and can be designated as Advance, Preliminary, or Production. Note that Virtex-II Pro Performance Characteristics are subject to these guidelines, as well. Each designation is defined as follows:

Advance: These speed files are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary: These speed files are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Production: These speed files are released once enough production silicon of a particular device family member has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

Since individual family members are produced at different times, the migration from one category to another depends completely on the status of the fabrication process for each device. Table 15 correlates the current status of each Virtex-II Pro device with a corresponding speed file designation.

All specifications are always representative of worst-case supply voltage and junction temperature conditions.

Table 15: **Virtex-II Pro Device Speed Grade Designations**

Device	Speed Grade Designations		
	Advance	Preliminary	Production
XC2VP2			-7, -6, -5
XC2VP4			-7, -6, -5
XC2VP7			-7, -6, -5
XC2VP20			-7, -6, -5
XC2VPX20		-6, -5	
XC2VP30			-7, -6, -5
XC2VP40			-7, -6, -5
XC2VP50			-7, -6, -5
XC2VP70			-7, -6, -5
XC2VPX70		-6, -5	
XC2VP100			-6, -5

Testing of Switching Characteristics

All devices are 100% functionally tested. Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer (TRCE in the Xilinx Development System) and back-annotate to the simulation net list. Unless otherwise noted, values apply to all Virtex-II Pro devices.

PowerPC Switching Characteristics

Table 16: **Processor Clocks Absolute AC Characteristics**

	Speed Grade						
	-7		-6		-5		
Description	Min	Max	Min	Max	Min	Max	Units
CPMC405CLOCK frequency	0	400(1)	0	350(1)	0	300	MHz
JTAGC405TCK frequency(2)	0	200	0	175	0	150	MHz
PLBCLK(3)	0	400	0	350	0	300	MHz
BRAMDSOCMCLK(3)	0	400	0	350	0	300	MHz
BRAMISOCMCLK(3)	0	400	0	350	0	300	MHz

Notes:

1. **IMPORTANT!** When CPMC405CLOCK runs at speeds greater than 350 MHz in -7 Commercial grade dual-processor devices, or greater than 300 MHz in -6 Industrial grade dual-processor devices, users must implement the technology presented in **XAPP755**, "PowerPC 405 Clock Macro for -7(C) and -6(I) Speed Grade Dual-Processor Devices." Refer to Table 1, Module 1 to identify dual-processor devices.
2. The theoretical maximum frequency of this clock is one-half the CPMC405CLOCK. However, the achievable maximum is dependent on the system, and will be much less.
3. The theoretical maximum frequency of these clocks is equal to the CPMC405CLOCK. However, the achievable maximum is dependent on the system. Please see ***PowerPC 405 Processor Block Reference Guide*** and **XAPP640** for more information.

RocketIO Switching Characteristics

Table 22: **RocketIO X Reference Clock Switching Characteristics**

			All Speed Grades			
Description	**Symbol**	**Conditions**	**Min**	**Typ**	**Max**	**Units**
Reference Clock frequency range(1)	F_{GCLK}		62.5		425	MHz
Reference Clock frequency tolerance	F_{GTOL}				±350	ppm
Reference Clock rise time	T_{RCLK}	20% – 80%		75		ps
Reference Clock fall time	T_{FCLK}	20% – 80%		75		ps
Reference Clock duty cycle	T_{DCREF}		45	50	55	%
Reference Clock total jitter, peak-peak	T_{GJTT}	3.125 Gb/s – 6.25 Gb/s			30	ps
		2.488 Gb/s – 3.125 Gb/s			40	ps
Clock recovery frequency acquisition time, from Power-up to High state of PMARXLOCK	T_{LOCK}			100		µs
Clock recovery phase acquisition time, from Data to High state of PMARXLOCK	T_{PHASE}			40	60	µs

Notes:
1. BREFCLK should be used for all serial bit rates up to the maximum shown.

Table 23: **RocketIO Reference Clock Switching Characteristics**

			All Speed Grades			
Description	**Symbol**	**Conditions**	**Min**	**Typ**	**Max**	**Units**
Reference Clock frequency range(1)	F_{GCLK}	Full rate operation	50		156.25	MHz
		Half rate operation(2) (2X oversampling)	60		100	MHz
Reference Clock frequency tolerance	F_{GTOL}				±100	ppm
Reference Clock rise time	T_{RCLK}	20% – 80%		600	1000	ps
Reference Clock fall time	T_{FCLK}	20% – 80%		600	1000	ps
Reference Clock duty cycle	T_{DCREF}		45	50	55	%
Reference Clock total jitter, peak-peak(3)	T_{GJTT}	2.501 Gb/s – 3.125 Gb/s			40	ps
		1.061 Gb/s – 2.5 Gb/s			50	ps
		< 1.06 Gb/s			120	ps
Clock recovery frequency acquisition time	T_{LOCK}				10	µs
Clock recovery phase acquisition time	T_{PHASE}			960		bits(4)

Notes:
1. BREFCLK/BREFCLK2 can be used for all serial bit rates up to the maximum shown. REFCLK/REFCLK2 can be used for serial bit rates up to 2.5 Gb/s (REFCLK = 125 MHz). All other parameters apply equally to REFCLK, REFCLK2, BREFCLK, and BREFCLK2 except as noted.
2. For serial rates under 1 Gb/s, the 3X (or greater) oversampling techniques described in **XAPP572** are required to meet the transmit jitter and receive jitter tolerance specifications defined in this data sheet.
3. Measured at the package pin. For reference clock frequencies equal to or above 125 MHz, BREFCLK/BREFCLK2 must be used.
4. 8B/10B-type bitstream.

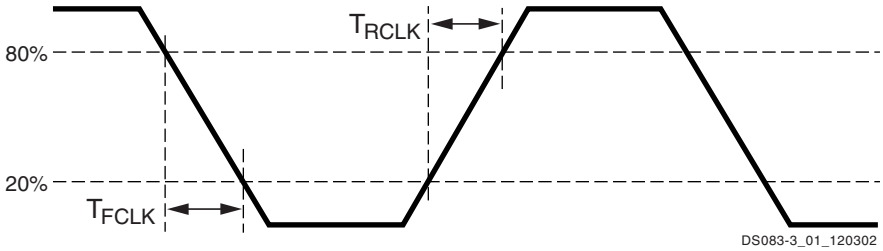

Figure 3: **Reference Clock Timing Parameters**

Table 27: **RocketIO Transmitter Switching Characteristics**

Description	Symbol	Conditions	Min	Typ	Max	Units
Serial data rate, full-speed clock	F_{GTX}	Flipchip packages	1.0		3.125(1)	Gb/s
		Wirebond packages	1.0		2.5(1)	Gb/s
Serial data rate, half-speed clock(3) (2X oversampling)		Flipchip packages	0.600		1.0	Gb/s
		Wirebond packages	0.600		1.0	Gb/s
Serial data output deterministic jitter	T_{DJ}	2.126 Gb/s – 3.125 Gb/s			0.17	UI(2)
		1.0626 Gb/s – 2.125 Gb/s			0.08	UI
		1.0 Gb/s – 1.0625 Gb/s			0.05	UI
		600 Mb/s – 999 Mb/s			0.08(4)	UI
Serial data output random jitter	T_{RJ}	2.126 Gb/s – 3.125 Gb/s			0.18	UI
		1.0626 Gb/s – 2.125 Gb/s			0.19	UI
		1.0 Gb/s – 1.0625 Gb/s			0.18	UI
		600 Mb/s – 999 Mb/s			0.18(4)	UI
TX rise time	T_{RTX}	20% – 80%		120		ps
TX fall time	T_{FTX}			120		ps
Transmit latency(5)	T_{TXLAT}	Including CRC		14	17	TXUSRCLK cycles
		Excluding CRC		8	11	
TXUSRCLK duty cycle	T_{TXDC}		45	50	55	%
TXUSRCLK2 duty cycle	T_{TX2DC}		45	50	55	%

Notes:
1. Serial data rate in the -5 speed grade is limited to 2.0 Gb/s in both wirebond and flipchip packages.
2. UI = Unit Interval
3. For serial rates under 1 Gb/s, the 3X (or greater) oversampling techniques described in **XAPP572** are required to meet the transmit jitter and receive jitter tolerance specifications defined in this data sheet.
4. The oversampling techniques described in **XAPP572** are required to meet these specifications for serial rates less than 1 Gb/s.
5. Transmit latency delay TXDATA to TXP/TXN. Refer to ***RocketIO Transceiver User Guide*** for more information on calculating latency.

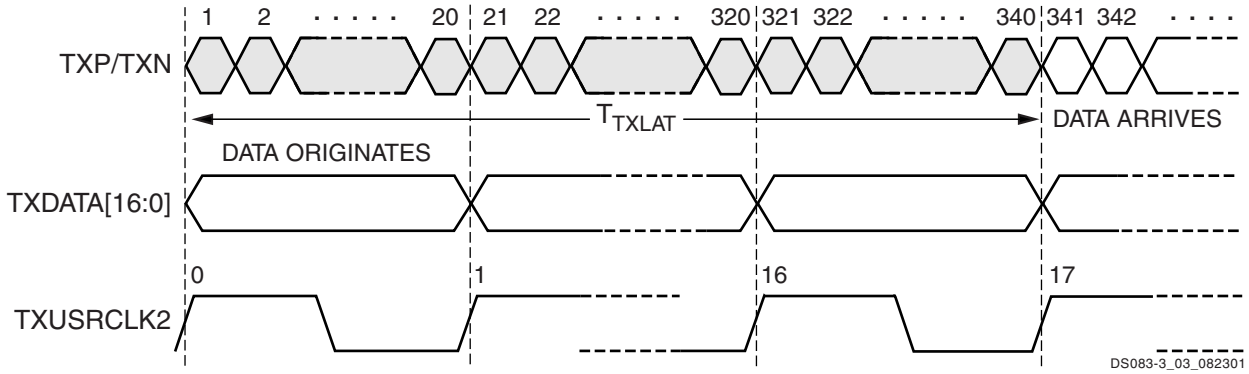

Figure 5: **RocketIO Transmit Latency (Maximum, Including CRC)**

Global Clock Set-Up and Hold for LVCMOS25 Standard, *Without* DCM

Table 56: **Global Clock Set-Up and Hold for LVCMOS25 Standard, *Without* DCM**

			Speed Grade			
Description	**Symbol**	**Device**	**-7**	**-6**	**-5**	**Units**
Input Setup and Hold Time Relative to Global Clock Input Signal for LVCMOS25 Standard. For data input with different standards, adjust the setup time delay by the values shown in IOB Input Switching Characteristics Standard Adjustments, page 25.						
Full Delay Global Clock and IFF without DCM	T_{PSFD}/T_{PHFD}	XC2VP2	1.80/–0.44	1.85/–0.41	1.96/–0.43	ns
		XC2VP4	1.82/–0.53	1.83/–0.31	1.90/–0.29	ns
		XC2VP7	1.80/–0.34	1.81/–0.24	1.88/–0.19	ns
		XC2VP20	1.76/–0.24	1.83/–0.17	1.92/–0.15	ns
		XC2VPX20	1.76/–0.24	1.83/–0.17	1.92/–0.15	ns
		XC2VP30	1.75/–0.22	1.92/–0.26	1.99/–0.23	ns
		XC2VP40	2.25/–0.54	2.40/–0.56	2.49/–0.54	ns
		XC2VP50	2.93/–1.02	2.98/–0.93	3.00/–0.83	ns
		XC2VP70	2.79/–0.72	2.79/–0.55	2.78/–0.41	ns
		XC2VPX70	2.79/–0.72	2.79/–0.55	2.78/–0.41	ns
		XC2VP100	N/A	5.58/–2.35	5.60/–2.35	ns

Notes:
1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

Table 5: **FG256/FGG256 — XC2VP2 and XC2VP4**

Bank	Pin Description	Pin Number
N/A	AVCCAUXRX7	B13
N/A	AVCCAUXRX18	R13
N/A	VTRXPAD18	R12
N/A	RXNPAD18	T13
N/A	RXPPAD18	T12
N/A	GNDA18	P11
N/A	TXPPAD18	T11
N/A	TXNPAD18	T10
N/A	VTTXPAD18	R10
N/A	AVCCAUXTX18	R11
N/A	AVCCAUXRX19	R7
N/A	VTRXPAD19	R6
N/A	RXNPAD19	T7
N/A	RXPPAD19	T6
N/A	GNDA19	P6
N/A	TXPPAD19	T5
N/A	TXNPAD19	T4
N/A	VTTXPAD19	R4
N/A	AVCCAUXTX19	R5
N/A	VCCINT	N4
N/A	VCCINT	N13
N/A	VCCINT	M5
N/A	VCCINT	M12
N/A	VCCINT	E5
N/A	VCCINT	E12
N/A	VCCINT	D4
N/A	VCCINT	D13
N/A	VCCAUX	R16
N/A	VCCAUX	R1
N/A	VCCAUX	B16
N/A	VCCAUX	B1
N/A	GND	T16
N/A	GND	T1
N/A	GND	R2

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
1	IO_L07P_1	F14			
1	IO_L06N_1	C15			
1	IO_L06P_1	D15			
1	IO_L05_1/No_Pair	E15			
1	IO_L03N_1/VREF_1	C16			
1	IO_L03P_1	D16			
1	IO_L02N_1	E16			
1	IO_L02P_1	E17			
1	IO_L01N_1/VRP_1	D17			
1	IO_L01P_1/VRN_1	D18			
2	IO_L01N_2/VRP_2	C21			
2	IO_L01P_2/VRN_2	C22			
2	IO_L02N_2	D21			
2	IO_L02P_2	D22			
2	IO_L03N_2	E19			
2	IO_L03P_2	E20			
2	IO_L04N_2/VREF_2	E21			
2	IO_L04P_2	E22			
2	IO_L06N_2	F19			
2	IO_L06P_2	F20			
2	IO_L43N_2	F21	NC		
2	IO_L43P_2	F22	NC		
2	IO_L46N_2/VREF_2	F18	NC		
2	IO_L46P_2	G18	NC		
2	IO_L48N_2	G19	NC		
2	IO_L48P_2	G20	NC		
2	IO_L49N_2	G21	NC		
2	IO_L49P_2	G22	NC		
2	IO_L50N_2	H19	NC		
2	IO_L50P_2	H20	NC		
2	IO_L52N_2/VREF_2	H21	NC		
2	IO_L52P_2	H22	NC		
2	IO_L54N_2	H18	NC		
2	IO_L54P_2	J17	NC		
2	IO_L55N_2	J19	NC		
2	IO_L55P_2	J20	NC		

FG676/FGG676 Fine-Pitch BGA Package

As shown in Table 7, XC2VP20, XC2VP30, and XC2VP40 Virtex-II Pro devices are available in the FG676/FGG676 fine-pitch BGA package. The pins in these devices are the same, except for the differences shown in the "No Connects" column. Following this table are the FG676/FGG676 Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
0	IO_L01N_0/VRP_0	E5			
0	IO_L01P_0/VRN_0	D5			
0	IO_L02N_0	E6			
0	IO_L02P_0	D6			
0	IO_L03N_0	G7			
0	IO_L03P_0/VREF_0	F7			
0	IO_L05_0/No_Pair	E7			
0	IO_L06N_0	D7			
0	IO_L06P_0	C7			
0	IO_L07N_0	H8			
0	IO_L07P_0	G8			
0	IO_L09N_0	F8			
0	IO_L09P_0/VREF_0	E8			
0	IO_L37N_0	B8			
0	IO_L37P_0	A8			
0	IO_L39N_0	H9			
0	IO_L39P_0	G9			
0	IO_L43N_0	F9			
0	IO_L43P_0	E9			
0	IO_L45N_0	D9			
0	IO_L45P_0/VREF_0	C9			
0	IO_L46N_0	H10			
0	IO_L46P_0	H11			
0	IO_L48N_0	E10			
0	IO_L48P_0	E11			
0	IO_L49N_0	D10			
0	IO_L49P_0	C10			
0	IO_L50_0/No_Pair	G11			
0	IO_L53_0/No_Pair	F11			
0	IO_L54N_0	J12			
0	IO_L54P_0	H12			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
0	IO_L55N_0	G12			
0	IO_L55P_0	F12			
0	IO_L57N_0	E12			
0	IO_L57P_0/VREF_0	F13			
0	IO_L67N_0	D12			
0	IO_L67P_0	C12			
0	IO_L69N_0	J13			
0	IO_L69P_0/VREF_0	H13			
0	IO_L74N_0/GCLK7P	E13			
0	IO_L74P_0/GCLK6S	D13			
0	IO_L75N_0/GCLK5P	C13			
0	IO_L75P_0/GCLK4S	B13			
1	IO_L75N_1/GCLK3P	B14			
1	IO_L75P_1/GCLK2S	C14			
1	IO_L74N_1/GCLK1P	D14			
1	IO_L74P_1/GCLK0S	E14			
1	IO_L69N_1/VREF_1	H14			
1	IO_L69P_1	J14			
1	IO_L67N_1	C15			
1	IO_L67P_1	D15			
1	IO_L57N_1/VREF_1	F14			
1	IO_L57P_1	E15			
1	IO_L55N_1	F15			
1	IO_L55P_1	G15			
1	IO_L54N_1	H15			
1	IO_L54P_1	J15			
1	IO_L53_1/No_Pair	F16			
1	IO_L50_1/No_Pair	G16			
1	IO_L49N_1	C17			
1	IO_L49P_1	D17			
1	IO_L48N_1	E16			
1	IO_L48P_1	E17			
1	IO_L46N_1	H16			
1	IO_L46P_1	H17			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	GND	H4			
N/A	GND	H23			
N/A	GND	K6			
N/A	GND	K21			
N/A	GND	L11			
N/A	GND	L12			
N/A	GND	L13			
N/A	GND	L14			
N/A	GND	L15			
N/A	GND	L16			
N/A	GND	M3			
N/A	GND	M11			
N/A	GND	M12			
N/A	GND	M13			
N/A	GND	M14			
N/A	GND	M15			
N/A	GND	M16			
N/A	GND	M24			
N/A	GND	N11			
N/A	GND	N12			
N/A	GND	N13			
N/A	GND	N14			
N/A	GND	N15			
N/A	GND	N16			
N/A	GND	P11			
N/A	GND	P12			
N/A	GND	P13			
N/A	GND	P14			
N/A	GND	P15			
N/A	GND	P16			
N/A	GND	R3			
N/A	GND	R11			
N/A	GND	R12			
N/A	GND	R13			
N/A	GND	R14			

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
2	IO_L05N_2	J8				
2	IO_L05P_2	J7				
2	IO_L06N_2	F5				
2	IO_L06P_2	F4				
2	IO_L15N_2	G4	NC			
2	IO_L15P_2	G3	NC			
2	IO_L16N_2/VREF_2	G6	NC			
2	IO_L16P_2	G5	NC			
2	IO_L17N_2	F2	NC			
2	IO_L17P_2	F1	NC			
2	IO_L18N_2	L10	NC			
2	IO_L18P_2	L9	NC			
2	IO_L19N_2	H6	NC			
2	IO_L19P_2	H5	NC			
2	IO_L20N_2	G2	NC			
2	IO_L20P_2	G1	NC			
2	IO_L21N_2	J6	NC			
2	IO_L21P_2	J5	NC			
2	IO_L22N_2/VREF_2	J4	NC			
2	IO_L22P_2	J3	NC			
2	IO_L23N_2	K8	NC			
2	IO_L23P_2	K7	NC			
2	IO_L24N_2	H4	NC			
2	IO_L24P_2	H3	NC			
2	IO_L31N_2	H2				
2	IO_L31P_2	H1				
2	IO_L32N_2	M10				
2	IO_L32P_2	M9				
2	IO_L33N_2	K5				
2	IO_L33P_2	K4				
2	IO_L34N_2/VREF_2	J2				
2	IO_L34P_2	K2				
2	IO_L35N_2	L8				
2	IO_L35P_2	L7				
2	IO_L36N_2	L6				
2	IO_L36P_2	L5				
2	IO_L37N_2	K1				
2	IO_L37P_2	L1				

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
6	IO_L25N_6	AH29		
6	IO_L26P_6	AE28		
6	IO_L26N_6	AD28		
6	IO_L27P_6	AG32		
6	IO_L27N_6/VREF_6	AG33		
6	IO_L28P_6	AH32		
6	IO_L28N_6	AG31		
6	IO_L29P_6	AE26		
6	IO_L29N_6	AD26		
6	IO_L30P_6	AG29		
6	IO_L30N_6	AG30		
6	IO_L31P_6	AF32		
6	IO_L31N_6	AF33		
6	IO_L32P_6	AC26		
6	IO_L32N_6	AC27		
6	IO_L33P_6	AF28		
6	IO_L33N_6/VREF_6	AF29		
6	IO_L34P_6	AE33		
6	IO_L34N_6	AE34		
6	IO_L35P_6	AD25		
6	IO_L35N_6	AC25		
6	IO_L36P_6	AF31		
6	IO_L36N_6	AE31		
6	IO_L37P_6	AE29		
6	IO_L37N_6	AE30		
6	IO_L38P_6	AC28		
6	IO_L38N_6	AB27		
6	IO_L39P_6	AD33		
6	IO_L39N_6/VREF_6	AD34		
6	IO_L40P_6	AE32		
6	IO_L40N_6	AD32		
6	IO_L41P_6	AB24		
6	IO_L41N_6	AB25		
6	IO_L42P_6	AD29		
6	IO_L42N_6	AD30		
6	IO_L43P_6	AC33		
6	IO_L43N_6	AC34		
6	IO_L44P_6	AA27		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
1	IO_L64N_1	E18		
1	IO_L64P_1	D18		
1	IO_L60N_1	G18		
1	IO_L60P_1	F18		
1	IO_L59N_1	L18		
1	IO_L59P_1	K18		
1	IO_L58N_1	J18		
1	IO_L58P_1	H18		
1	IO_L57N_1/VREF_1	D17		
1	IO_L57P_1	C17		
1	IO_L56N_1	N18		
1	IO_L56P_1	M18		
1	IO_L55N_1	E17		
1	IO_L55P_1	E16		
1	IO_L54N_1	G17		
1	IO_L54P_1	F16		
1	IO_L53_1/No_Pair	J17		
1	IO_L50_1/No_Pair	H17		
1	IO_L49N_1	J16		
1	IO_L49P_1	H16		
1	IO_L48N_1	D15		
1	IO_L48P_1	C15		
1	IO_L47N_1	L17		
1	IO_L47P_1	K16		
1	IO_L46N_1	F15		
1	IO_L46P_1	E15		
1	IO_L45N_1/VREF_1	H15		
1	IO_L45P_1	G15		
1	IO_L44N_1	N17		
1	IO_L44P_1	M17		
1	IO_L43N_1	D14		
1	IO_L43P_1	C14		
1	IO_L39N_1	F14		
1	IO_L39P_1	E14		
1	IO_L38N_1	M16		
1	IO_L38P_1	M15		
1	IO_L37N_1	H14		
1	IO_L37P_1	G14		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
4	IO_L03N_4/D2	AN10		
4	IO_L03P_4/D3	AM10		
4	IO_L05_4/No_Pair	AK10		
4	IO_L06N_4/VRP_4	AR10		
4	IO_L06P_4/VRN_4	AP10		
4	IO_L07N_4	AU10		
4	IO_L07P_4/VREF_4	AT10		
4	IO_L08N_4	AJ12		
4	IO_L08P_4	AJ13		
4	IO_L09N_4	AL10		
4	IO_L09P_4/VREF_4	AL11		
4	IO_L19N_4	AN11		
4	IO_L19P_4	AM11		
4	IO_L20N_4	AH13		
4	IO_L20P_4	AH14		
4	IO_L21N_4	AR11		
4	IO_L21P_4	AP11		
4	IO_L25N_4	AU11		
4	IO_L25P_4	AT11		
4	IO_L26N_4	AL14		
4	IO_L26P_4	AK14		
4	IO_L27N_4	AM12		
4	IO_L27P_4/VREF_4	AL12		
4	IO_L28N_4	AT12	NC	
4	IO_L28P_4	AR12	NC	
4	IO_L29N_4	AJ14	NC	
4	IO_L29P_4	AJ15	NC	
4	IO_L30N_4	AM13	NC	
4	IO_L30P_4	AL13	NC	
4	IO_L34N_4	AP12	NC	
4	IO_L34P_4	AN13	NC	
4	IO_L35N_4	AL15	NC	
4	IO_L35P_4	AK15	NC	
4	IO_L36N_4	AT13	NC	
4	IO_L36P_4/VREF_4	AR13	NC	
4	IO_L37N_4	AN14		
4	IO_L37P_4	AM14		
4	IO_L38N_4	AH15		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
1	IO_L48N_1		J17		
1	IO_L48P_1		H17		
1	IO_L47N_1		K17		
1	IO_L47P_1		L17		
1	IO_L46N_1		M17		
1	IO_L46P_1		M18		
1	IO_L45N_1/VREF_1		F16		
1	IO_L45P_1		E16		
1	IO_L44N_1		G16		
1	IO_L44P_1		H16		
1	IO_L43N_1		K16		
1	IO_L43P_1		J16		
1	IO_L39N_1		M16		
1	IO_L39P_1		L16		
1	IO_L38N_1		C15		
1	IO_L38P_1		C14		
1	IO_L37N_1		F15		
1	IO_L37P_1		E15		
1	IO_L87N_1/VREF_1		J15	NC	
1	IO_L87P_1		H15	NC	
1	IO_L86N_1		K15	NC	
1	IO_L86P_1		L15	NC	
1	IO_L85N_1		E14	NC	
1	IO_L85P_1		D14	NC	
1	IO_L84N_1		G14	NC	
1	IO_L84P_1		F14	NC	
1	IO_L83_1/No_Pair		H14	NC	
1	IO_L78N_1		L14	NC	
1	IO_L78P_1		K14	NC	
1	IO_L36N_1/VREF_1		M14		
1	IO_L36P_1		M15		
1	IO_L35N_1		C13		
1	IO_L35P_1		D13		
1	IO_L34N_1		F13		
1	IO_L34P_1		E13		
1	IO_L30N_1		H13		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
2	IO_L44P_2		U10		
2	IO_L45N_2		U3		
2	IO_L45P_2		U4		
2	IO_L46N_2/VREF_2		U1		
2	IO_L46P_2		U2		
2	IO_L47N_2		T12		
2	IO_L47P_2		U12		
2	IO_L48N_2		V10		
2	IO_L48P_2		V11		
2	IO_L49N_2		V7		
2	IO_L49P_2		V8		
2	IO_L50N_2		U11		
2	IO_L50P_2		V12		
2	IO_L51N_2		V4		
2	IO_L51P_2		V5		
2	IO_L52N_2/VREF_2		V1		
2	IO_L52P_2		V2		
2	IO_L53N_2		W9		
2	IO_L53P_2		W10		
2	IO_L54N_2		W7		
2	IO_L54P_2		W8		
2	IO_L55N_2		W5		
2	IO_L55P_2		W6		
2	IO_L56N_2		W11		
2	IO_L56P_2		W12		
2	IO_L57N_2		W3		
2	IO_L57P_2		W4		
2	IO_L58N_2/VREF_2		W1		
2	IO_L58P_2		W2		
2	IO_L59N_2		Y9		
2	IO_L59P_2		Y10		
2	IO_L60N_2		Y6		
2	IO_L60P_2		Y7		
2	IO_L85N_2		Y3		
2	IO_L85P_2		Y4		
2	IO_L86N_2		Y11		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
6	IO_L34N_6		AH38		
6	IO_L35P_6		AH31		
6	IO_L35N_6		AH32		
6	IO_L36P_6		AJ40		
6	IO_L36N_6		AH40		
6	IO_L37P_6		AH41		
6	IO_L37N_6		AH42		
6	IO_L38P_6		AH35		
6	IO_L38N_6		AG35		
6	IO_L39P_6		AG36		
6	IO_L39N_6/VREF_6		AG37		
6	IO_L40P_6		AG38		
6	IO_L40N_6		AG39		
6	IO_L41P_6		AG32		
6	IO_L41N_6		AG33		
6	IO_L42P_6		AG40		
6	IO_L42N_6		AG41		
6	IO_L43P_6		AF33		
6	IO_L43N_6		AF34		
6	IO_L44P_6		AF35		
6	IO_L44N_6		AF36		
6	IO_L45P_6		AF37		
6	IO_L45N_6/VREF_6		AF38		
6	IO_L46P_6		AF39		
6	IO_L46N_6		AF40		
6	IO_L47P_6		AF31		
6	IO_L47N_6		AG31		
6	IO_L48P_6		AF41		
6	IO_L48N_6		AF42		
6	IO_L49P_6		AE35		
6	IO_L49N_6		AE36		
6	IO_L50P_6		AE31		
6	IO_L50N_6		AF32		
6	IO_L51P_6		AE38		
6	IO_L51N_6/VREF_6		AE39		
6	IO_L52P_6		AE41		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	GND		E22		
N/A	GND		E21		
N/A	GND		E5		
N/A	GND		D39		
N/A	GND		D32		
N/A	GND		D28		
N/A	GND		D15		
N/A	GND		D11		
N/A	GND		D4		
N/A	GND		C42		
N/A	GND		C41		
N/A	GND		C40		
N/A	GND		C3		
N/A	GND		C2		
N/A	GND		C1		
N/A	GND		B42		
N/A	GND		B1		
N/A	GND		N14		
N/A	GND		N29		
N/A	GND		AK14		
N/A	GND		AK29		
N/A	GND		P13		
N/A	GND		P30		
N/A	GND		AJ13		
N/A	GND		AJ30		

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L08N_7	N35	
7	IO_L07P_7	G41	
7	IO_L07N_7	G42	
7	IO_L72P_7	G39	
7	IO_L72N_7	G40	
7	IO_L71P_7	P32	
7	IO_L71N_7	P33	
7	IO_L70P_7	F38	
7	IO_L70N_7/VREF_7	G38	
7	IO_L69P_7	F37	
7	IO_L69N_7	G37	
7	IO_L68P_7	N32	
7	IO_L68N_7	N33	
7	IO_L67P_7	G35	
7	IO_L67N_7	G36	
7	IO_L66P_7	F41	
7	IO_L66N_7	F42	
7	IO_L65P_7	P31	
7	IO_L65N_7	N31	
7	IO_L64P_7	E41	
7	IO_L64N_7/VREF_7	F40	
7	IO_L63P_7	E36	
7	IO_L63N_7	F36	
7	IO_L62P_7	M34	
7	IO_L62N_7	M35	
7	IO_L61P_7	E35	
7	IO_L61N_7	F35	
7	IO_L84P_7	D40	
7	IO_L84N_7	E40	
7	IO_L83P_7	L34	
7	IO_L83N_7	L35	
7	IO_L82P_7	D39	
7	IO_L82N_7/VREF_7	E39	
7	IO_L81P_7	D38	
7	IO_L81N_7	E37	
7	IO_L80P_7	K34	
7	IO_L80N_7	J35	

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
08/14/02	2.0	Added package and pinout information for new devices.
08/27/02	2.1	• Updated SelectIO-Ultra information in Table 4. (Table deleted in v2.3.) • Corrected direction for RXNPAD and TXPPAD in Table 4 (formerly Table 5).
09/27/02	2.2	Corrected Table 2 and Table 3 entries for XC2VP30, FF1152 package, maximum I/Os from 692 to 644.
11/20/02	2.3	Added Number of Differential Pairs data to Table 3. Removed former Table 4.
12/03/02	2.4	Corrections in Table 4: • Reclassified GCLKx (S/P) pins as Input/Output, since these pins can be used as normal I/Os if not used as clocks. • Added cautionary note to PWRDWN_B pin, indicating that this function is not supported.
01/20/03	2.5	Added and removed package/pinout information for existing devices: • In Table 1, added FG676 package information. • In Table 3, added FG676 package option for XC2VP20, XC2VP30, and XC2VP40. • In Table 12, removed FF1517 package option for XC2VP40. • Added FG676 package pinouts (Table 7) for XC2VP20, XC2VP30, and XC2VP40. • Added package diagram (Figure 3) for FG676 package.
05/19/03	2.5.1	• Added section **BREFCLK Pin Definitions**, page 5. • Added clarification to Table 4 and all device pinout tables regarding the dual-use nature of pins D0/DIN and BUSY/DOUT during configuration.
06/19/03	2.5.3	• Added notation of "open-drain" to TDO pin in Table 4. • The final GND pin in each of six pinout tables was inadvertently deleted in v2.5.1. This revision restores the deleted GND pins as follows: - Pin A1, Table 6, page 16 (FG456) - Pin AF26, Table 7, page 30 (FG676) - Pin AN34, Table 10, page 98 (FF1152) - Pin E1, Table 11, page 130 (FF1148) - Pin C38, Table 12, page 162 (FF1517) - Pin E1, Table 14, page 253 (FF1696)
08/25/03	2.5.5	• Table 4: Deleted Note 2, obsolete. There is only one GNDA pin per MGT. • Table 4: Deleted pins ALT_VRP and ALT_VRN. Not used in Virtex-II Pro FPGAs.
12/10/03	3.0	• XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, are released to **Production status**.
02/19/04	3.1	• Table 4, signal descriptions column: - For signals TDI, TMS, and TCK, added: Pins are 3.3V-compatible. - For signals M2, M1, M0, added: Tie to 3.3V only with 100Ω series resistor. No toggling during or after configuration. - For signal TDO, added: No internal pull-up. External pull-up to 3.3V OK with resistor greater than 200Ω.
03/09/04	3.1.1	• Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
06/30/04	4.0	Merged in DS110-4 (Module 4 of Virtex-II Pro X data sheet). Added data on available Pb-free packages and updated package diagrams for affected devices.